

Product name

FC-135 32.768000 kHz 6.0 +10.0-10.0

Product Number / Ordering code

Q13FC13500060xx

Please refer to the 5.Packing information about xx (last 2 digits)

Complies with EU RoHS directive

Reference weight Typ. 11 mg

1.Absolute maximum ratings						
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions / Remarks
Storage temperature	T_stg	-55	-	125	°C	Storage as single product
Maximum drive level	GL	-	-	0.5	μW	

2.Specificatioins(characteristics)						
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions / Remarks
Nominal frequency	f_nom	-	32.768	-	kHz	
Operating temperature	T_use	-40	-	85	°C	
Level of drive	DL	-	0.1	0.5	μW	
Frequency tolerance	f_tol	-10	-	+10.0	x 10 ⁻⁶	+25°C DL=0.1μW
Turnover temperature	Ti	20	25	30	°C	
Parabolic coefficient	B	-	-	-0.04	x 10 ⁻⁶ /°C ²	
Load capacitance	CL	-	6.0	-	pF	
Motional resistance (ESR)	R1	-	-	70	k Ω	
Motional capacitance	C1	-	3.4	-	fF	
Shunt capacitance	C0	-	1	-	pF	
Motional inductance	L1	-	7.1	-	kH	
Frequency aging	f_age	-3	-	3	x10 ⁻⁶ /yea	@+25°C, First year

3.External dimensions (Unit: mm)

Top view: 3.2±0.1, 1.5±0.1, C622J

Side view: 0.8±0.1

Bottom view: 1.7, 0.75, #1, #2

Internal Connection: #1, #2

4.Footprint(Recommended) (Unit: mm)

2.5, 1.8, 1.0

*Do not design any circuit patterns in the shaded area.

5.Packing information

[1]Product number last 2 digits code (xx) description

The recommended code is "00"

Q13FC13500060xx

Code	Condition	Code	Condition
01	Any Q'ty vinyl bag(Tape cut)	14	1000pcs / Reel
11	Any Q'ty / Reel	15	2000pcs / Reel
12	250pcs / Reel	00	3000pcs / Reel
13	500pcs / Reel		

[2] Taping specification

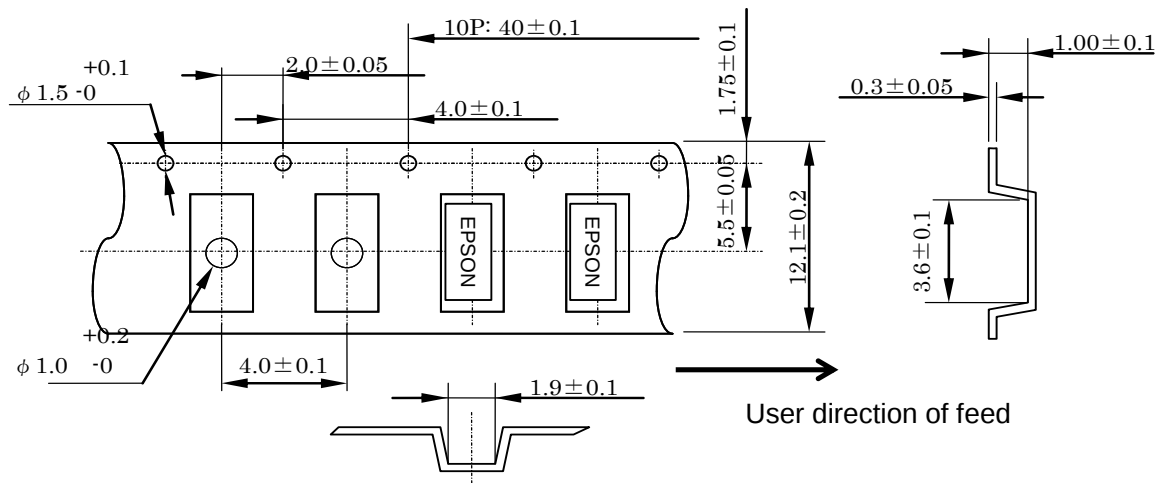
Subject to EIA-481 & IEC-60286

(1) Tape dimensions TE1204L

Material of the Carrier Tape : PS

Material of the Top Tape : PET+PE

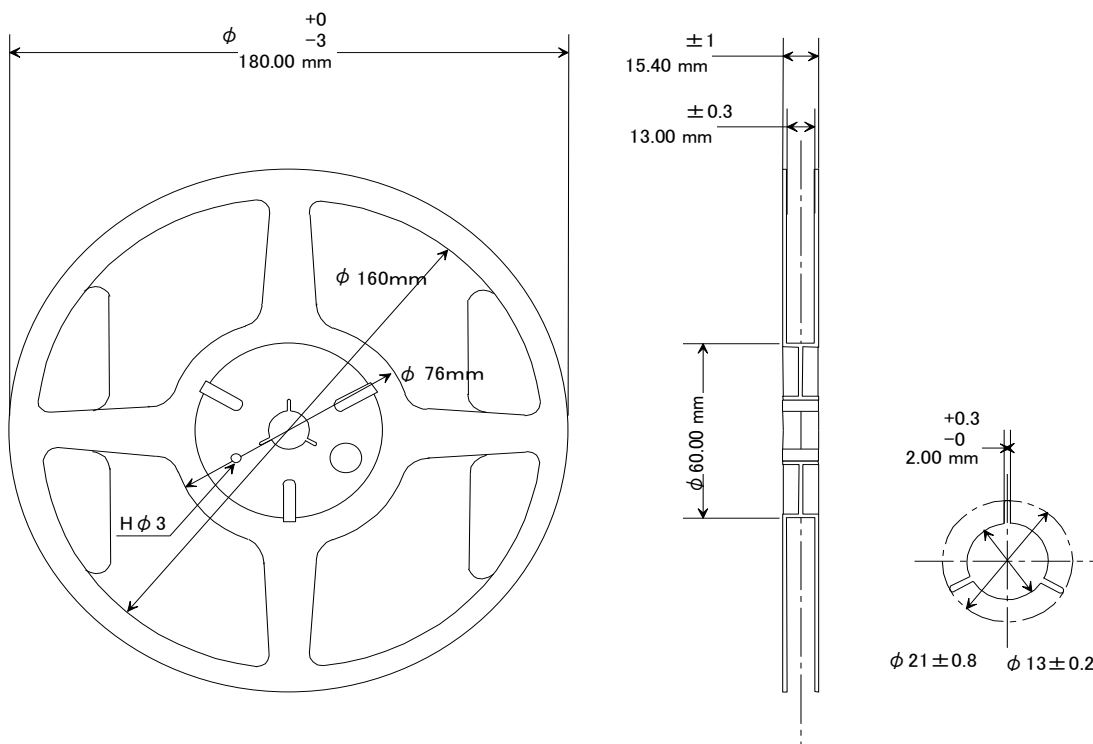
Unit: mm



(2) Reel dimensions

Material of the Reel : PS

Unit: mm



Reflow profile

Pre Heating Temperature

Tp1 ~ Tp2 = + 170 °C

Heating Temperature

T_{Mlt} = + 220 °C

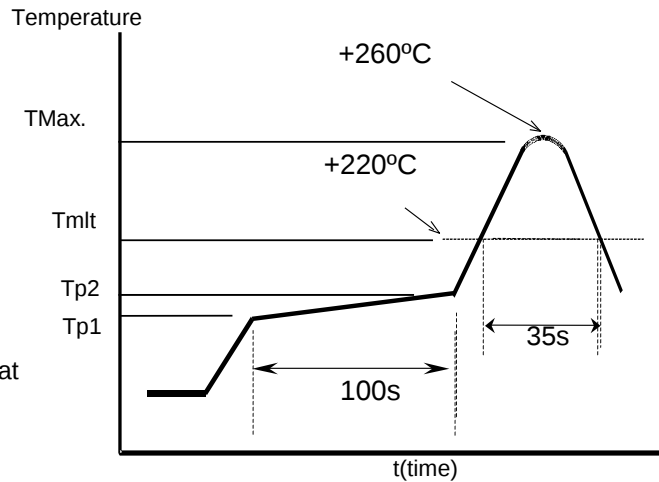
Peak Temperature

T_{Max.} = + 260 °C

Point of measuring

In case of Solder ability

Terminal.

In case of Resistance to soldering heat
Surface.**Notice****NOTICE: PLEASE READ CAREFULLY BELOW BEFORE THE USE OF THIS DOCUMENT**

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